Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

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**.090”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size = .004 x .004”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .090” X .129” DATE: 11/10/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .000” P/N: 1NA111**

**DG 10.1.2**

#### Rev B, 7/1